exhaust mechanism, a rising air current from the gap portion toward the pipe is formed between an outer surface of the substrate holding portion and an inner surface of the holding portion cover.

[0006]

A substrate polishing apparatus of another embodiment includes a rotating polishing table, a substrate holding portion that holds a substrate and presses the substrate against the polishing table to polish the substrate, and a local exhaust mechanism whose intake head is disposed near the substrate holding portion, in which the intake head is disposed on a downstream side of the substrate holding portion in a rotation direction of the polishing table.

[0006a] A substrate polishing apparatus of another embodiment includes:

a substrate holding portion that holds a substrate and presses the substrate against a polishing table to polish the substrate;

a pad cooling nozzle for cooling a polishing pad that polishes the substrate; and

a local exhaust mechanism whose intake head is disposed near the pad cooling nozzle, wherein

the intake head is disposed on a downstream side of the pad cooling nozzle in a rotation direction of the polishing table.

## BRIEF DESCRIPTION OF DRAWINGS

[0007]

FIG. 1 is a plan view illustrating a whole configuration of a substrate processing apparatus in a first embodiment;

[0008]

FIG. 2 is a perspective view illustrating a structure of a swing transporter in the first embodiment;

[0009]

FIG. 3(A) is a plan view illustrating a cleaning portion in the first embodiment, and FIG. 3(B) is a side